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# BK3231S Bluetooth SoC Datasheet

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## *Preliminary Specification*

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*Disclaimer: Descriptions of specific implementations are for illustrative purpose only, actual hardware implementation may differ.*



## *Revision History*

Rev.	Date	Author(s)	Remark
1.0	2015-1-7	Yiming and Guofei	Draft version based on BK3231 datasheet
1.1	2016-02-26	mingsheng	Add the 32PIN SIP package inf
1.2	2016.04.08	Mingsheng.ao	Modified the SIP package removed P22,P23,VPP, added P35,P36,P37 ,which is based on the SIP package
1.3	2016.04.11	Mingsheng.ao	Modified the Description

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## 1 General Description

### 1.1 Overview

The BK3231S chip is a highly integrated SoC, and it supports two wireless protocols, which are Bluetooth Basic Rate (BR), and Bluetooth Low Energy (BLE). It integrates a high-performance 2.4GHz RF transceiver, rich features baseband, ARM-core MCU and various peripheral IOs. It uses up-to-4Mbit external Flash to excute the programmable protocol and profile to support customized applications such as HID, Bluetooth 3D Glasses shutter, Remote controllers.

### 1.2 Block Diagram

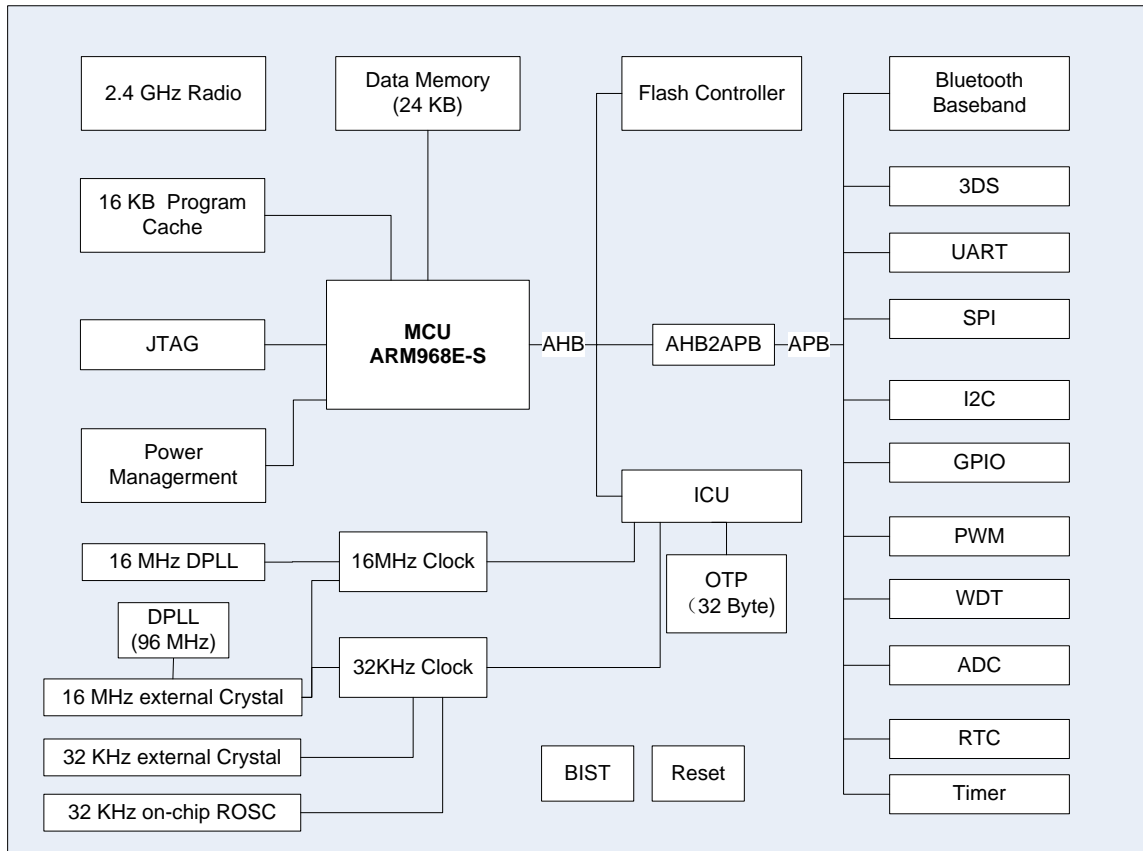


Figure 1 Block Diagram

### 1.3 Features

- Bluetooth® SIG Bluetooth Dual-Mode compliant
  - Bluetooth 3.0 Basic Rate (BR)
  - Bluetooth 4.0 Low Energy (BLE)
- ARM968 Core MCU integrated
- External Flash up-to-4Mbytes for Program and 24KB RAM for Data
- Low-power 2.4GHz Transceiver
- Operation voltage from 1.8V to 3.6 V
- -89 dBm sensitivity at 1 Mbps data rate and +4dBm transmit power for BLE application
- -86dBm sensitivity for 1 Mbps mode and 2 dBm transmit power for BR application
- External power-amplifier supporting
- Clock
  - 16 MHz crystal reference clock
  - 96MHz optional clock provided by internal DPLL
  - Internal 32kHz low-power oscillator with auto-calibration ( $\pm 200$ ppm)
  - External 32kHz crystal oscillator as optional low-power clock source
- Interface and peripheral units
  - FLASH programming, JTAG, Dual I2Cs, SPI and UART interface
  - Integrated OTP for customization
  - On-chip high accurate temperature sensor
  - On-chip 7-channel 10bit general ADC
  - 6-outputs PWM
  - 4-outputs 3D Glasses shutter
  - Real-time counter
- Package Type
  - 56-pin QFN 7mmx7mm package
  - 32-pin QFN 4mmx4mm package

### 1.4 Application

- Wireless Self-Timer
- Wireless Keyboards



- Wireless Mouse
- Wireless Gamepad
- LED Lighting Remote Control
- Bluetooth 3D Glasses



## 2 Pin Information

The QFN56 package format for the full functions usage. It can be used as keyboard TX part and total 34 GPIO available. The pin assignment for QFN56 package is shown in Figure 2. Other package type such as QFN32 is also available by request with less GPIO.

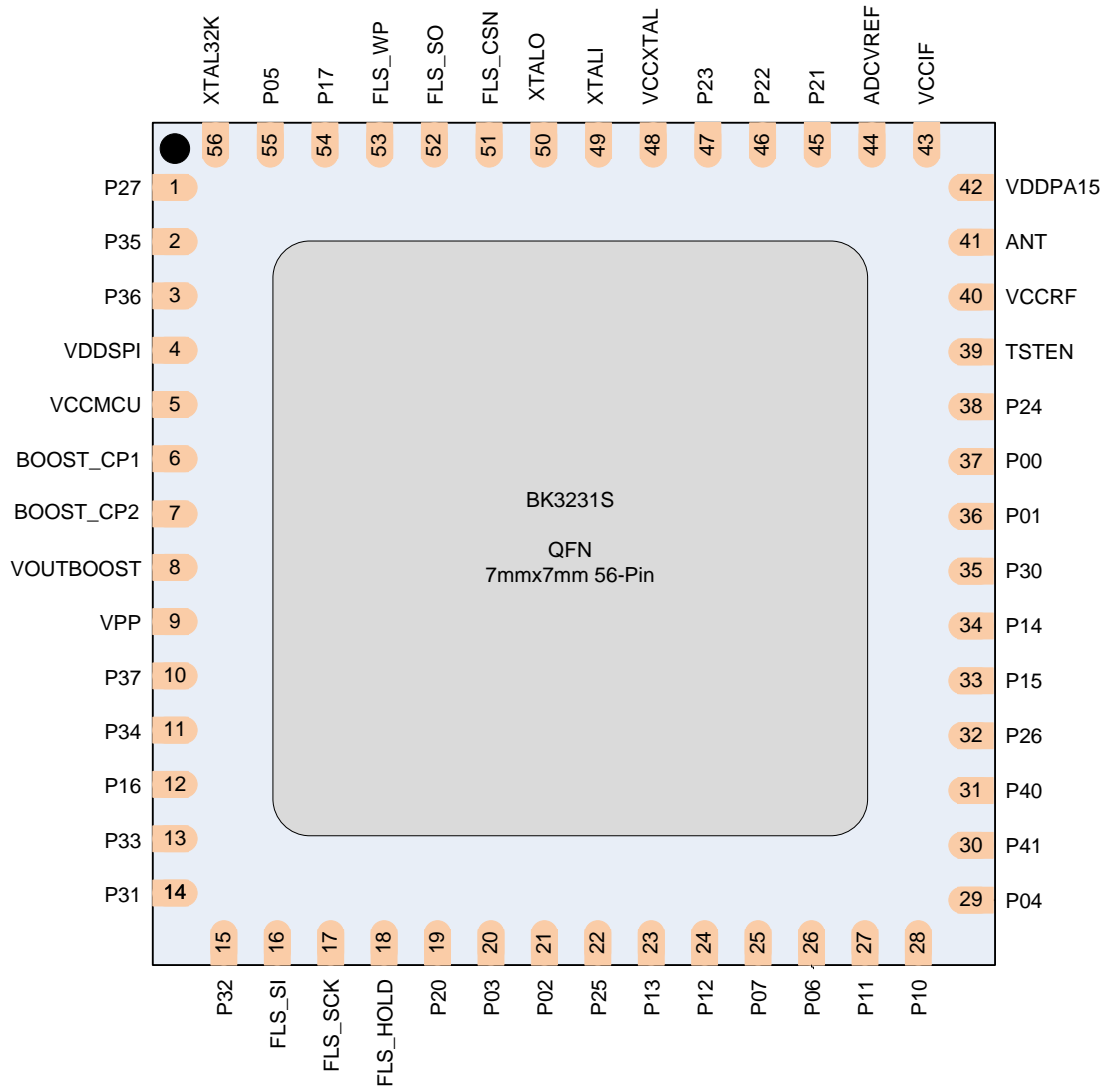


Figure 2 BK3231S QFN56Pin Assignment

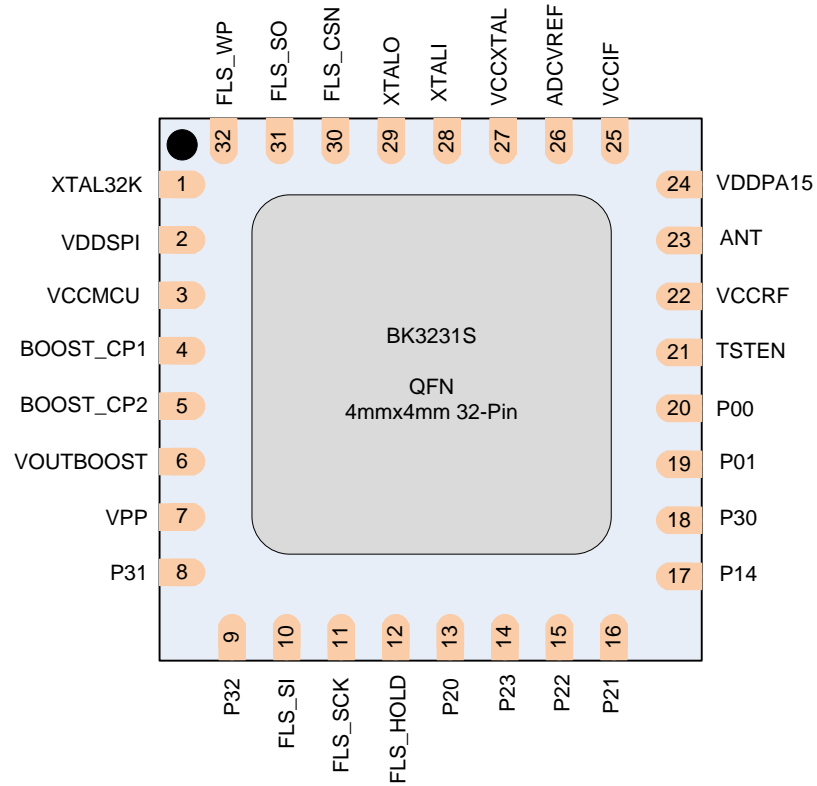
**Table 1 BK3231S QFN56 Pin Description**

NO	Name	Description
1	P27	General I/O
2	P35	General I/O, or input of ADC5
3	P36	General I/O, or input of ADC6
4	VDDSPI	The output of digital LDO
5	VCCMCU	3V power supply
6	boost_cp1	The function PIN of boost,add 100nF cap between boost_cp1 and boost_cp2
7	boost_cp2	The function PIN of boost,add 100nF cap between boost_cp1 and boost_cp2
8	voutboost	The output of boost
9	VPP	The 6V power supply of OTP,it can be used when download
10	P37	General I/O, or input of ADC7
11	P34	General I/O, or input of ADC4
12	P16	General I/O, or clock for I2C1
13	P33	General I/O, or input of ADC3
14	P31	General I/O, or input of ADC1
15	P32	General I/O, or input of ADC2
16	FLS_SI	The function PIN of flash
17	FLS_SCK	The function PIN of flash
18	FLS_HOLD	The function PIN of flash
19	P20	General I/O, or UART TX
20	P03	General I/O, or 3DS_PWM[3]
21	P02	General I/O, or 3DS_PWM[2]
22	P25	General I/O, or enable for TIMER1
23	P13	General I/O, or enable for PWM3
24	P12	General I/O, or enable for PWM2
25	P07	General I/O, or chip select for SPI
26	P06	General I/O,or MISO for SPI
27	P11	General I/O, or enable for PWM1
28	P10	General I/O, or enable for PWM0
29	P04	General I/O, or SCK for SPI
30	P41	General I/O, or PLL enable
31	P40	General I/O, or PA enable
32	P26	General I/O, or enable for TIMER2
33	P15	General I/O, or enable for PWM5
34	P14	General I/O, or enable for PWM4
35	P30	General I/O, or input of ADC0
36	P01	General I/O, or 3DS_PWM[1]
37	P00	General I/O, or 3DS_PWM[0]



38	P24	General I/O, or enable for TIMER0
39	TSTEN	Enable the testing function of memory
40	VCCRF	3V power supply
41	ANT	The input of RF
42	VDDPA15	The output of PA ldo
43	VCCIF	3V power supply
44	ADCVREF	The output of reference voltage of ADC,it can be connected to a cap on the board
45	P21	General I/O, or UART RX
46	P22	General I/O, or clock for I2C0
47	P23	General I/O, or data I/O for I2C0
48	VCCXTAL	3V power supply
49	XTALI	The input of 16M crystal oscillator
50	XTALO	The input of 16M crystal oscillator
51	FLS_CSN	The function PIN of flash
52	FLS_SO	The function PIN of flash
53	FLS_WP	The function PIN of flash
54	P17	General I/O, or data I/O for I2C1
55	P05	General I/O, or MOSI for SPI
56	XTAL32K	The input of 32K crystal oscillator

The pin assignment for QFN32 package is shown in Figure 3.

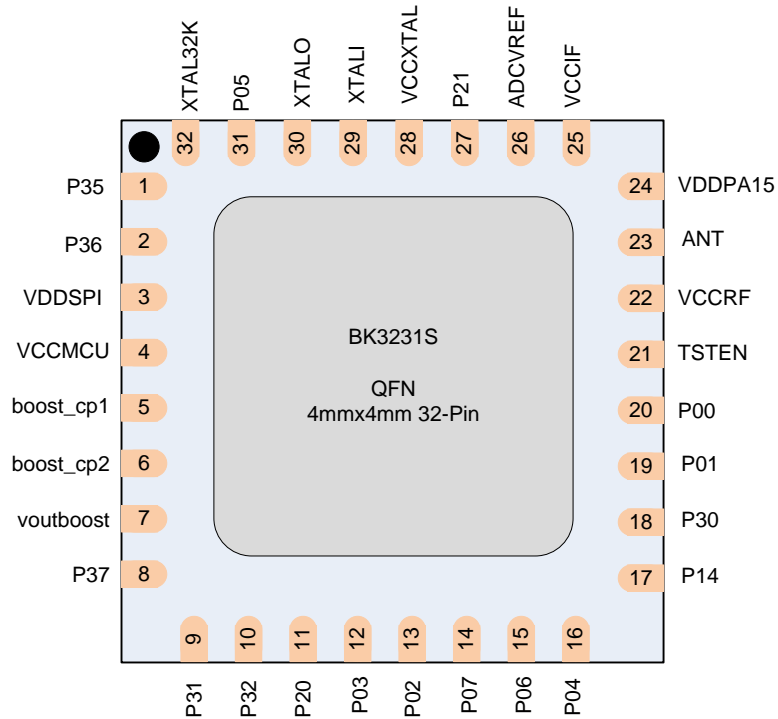


**Figure 3 BK3231S QFN32Pin Assignment**

**Table 2 BK3231S QFN32 Pin Description**

<b>NO</b>	<b>Name</b>	<b>Description</b>
1	XTAL32K	The input of 32K crystal oscillator
2	VDDSPI	The output of digital LDO
3	VCCMCU	3V power supply
4	boost_cp1	Boost function PIN. Add 100nF cap between boost_cp1 and boost_cp2
5	boost_cp2	Boost function PIN. Add 100nF cap between boost_cp1 and boost_cp2
6	voutboost	The output of boost
7	VPP	The 6V power supply of OTP,it can be used when download
8	P31	General I/O , or input of ADC1
9	P32	General I/O , or input of ADC2
10	FLS_SI	The function PIN of flash
11	FLS_SCK	The function PIN of flash
12	FLS_HOLD	The function PIN of flash
13	P20	General I/O, or UART TX
14	P23	General I/O , or data I/O for I2C0
15	P22	General I/O , or clock for I2C0
16	P21	General I/O, or UART RX
17	P14	General I/O , or enable for PWM4
18	P30	General I/O , or input of ADC0
19	P01	General I/O, or 3DS_PWM[1]
20	P00	General I/O, or 3DS_PWM[0]
21	TSTEN	Enable the testing function of memory
22	VCCRF	3V power supply
23	ANT	The input of RF
24	VDDPA15	The output of PA ldo
25	VCCIF	3V power supply
26	ADCVREF	The output of reference voltage of ADC. It can be connected to a cap on the board
27	VCCXTAL	3V power supply
28	XTALI	The input of 16M crystal oscillator
29	XTALO	The input of 16M crystal oscillator
30	FLS_CSN	The function PIN of flash
31	FLS_SO	The function PIN of flash
32	FLS_WP	The function PIN of flash

The pin assignment for QFN32 package(SIP with flash) is shown in Figure 4



**Figure 4 BK3231S QFN32Pin Assignment(SIP with flash)**

**Table 3 BK3231S QFN32 Pin Description(SIP with flash)**

NO	Name	Description
1	<b>P35</b>	<b>General I/O, or input of ADC1</b>
2	<b>P36</b>	<b>General I/O, or input of ADC1</b>
3	VDDSPI	The output of digital LDO
4	VCCMCU	3V power supply
5	boost_cp1	Boost function PIN. Add 100nF cap between boost_cp1 and boost_cp2
6	boost_cp2	Boost function PIN. Add 100nF cap between boost_cp1 and boost_cp2
7	voutboost	The output of boost
8	<b>P37</b>	<b>General I/O , or input of ADC1</b>
9	P31	General I/O , or input of ADC1
10	P32	General I/O , or input of ADC2
11	P20	General I/O, or UART TX



12	P03	General I/O, or 3DS_PWM[3], I2C1.SDA, WP_FL A
13	P02	General I/O, or 3DS_PWM[2], I2C1.SCL, HOLD_FL A
14	P07	General I/O, or SPI_NSS, CSN_FL A
15	P06	General I/O, or MISO for SPI, SCK_FL A
16	P04	General I/O, or SPI_SCK, SI_FL A
17	P14	General I/O , or enable for PWM4
18	P30	General I/O , or input of ADC0
19	P01	General I/O, or 3DS_PWM[1]
20	P00	General I/O, or 3DS_PWM[0]
21	TSTEN	Enable the testing function of memory
22	VCCRF	3V power supply
23	ANT	The input of RF
24	VDDPA15	The output of PA Ido
25	VCCIF	3V power supply
26	ADCVREF	The output of reference voltage of ADC. It can be connected to a cap on the board
27	P21	General I/O, or UART RX
28	VCCXTAL	3V power supply
29	XTALI	The input of 16M crystal oscillator
30	XTALO	The input of 16M crystal oscillator
31	P05	General I/O, or MOSI for SPI, SO_FL A
32	XTAL32K	The input of 32K crystal oscillator

## 3 Function Description

### 3.1 Memory Address Mapping

**Table 3 The Memory Mapping**

	Start Address	End Address	Total (Bytes)
<b>Program Memory</b>			
Flash space	0x00000000	0x0003FFFF	4M maximum
<b>Data Memory</b>			
SRAM	0x00400000	0x00405FFF	24K
<b>AHB Peripheral</b>			
ICU	0x00800000	0x0080FFFF	64K
BK24_BB	0x00810000	0x0081FFFF	64K
FLASH CONTROL	0x00820000	0x0082FFFF	64K
AHB2APB	0x00F00000	0x00FFFFFF	1M
<b>APB Peripheral</b>			
WDT	0x00F00000	0x00F000FF	256B
PWM	0x00F00100	0x00F001FF	256B
SPI	0x00F00200	0x00F002FF	256B
UART	0x00F00300	0x00F003FF	256B
I2C0	0x00F00400	0x00F004FF	256B
GPIO	0x00F00500	0x00F005FF	256B
RTC	0x00F00600	0x00F006FF	256B
ADC	0x00F00700	0x00F007FF	256B
BT 3DS	0x00F00800	0x00F008FF	256B
I2C1	0x00F00900	0x00F009FF	256B
Timer	0x00F00A00	0x00F00AFF	256B
XVR	0x00F10000	0x00F1FFFF	64K
CEVA DM IP	0x00F20000	0x00F2FFFF	64K



## 3.2 Interrupt and Clock Unit

The MCU core clock can be selected from three clock sources: 32KHz clock, 16 MHz clock and 96 MHz DPLL.

The ARM968E-S supports two interrupt level. The FIRQ has higher priority than nIRQ. In the BK3231S, all peripheral interrupts are nIRQ except the Bluetooth transceiver. All interrupt can be enabled, disabled, and cleared. There are two low power modes: MCU stop and deep sleep, and any interrupt can be configured to be a wake up source to let MCU exit low power mode.

## 3.3 GPIO

There are totally 40 general purpose input/output ports (GPIO). All the 40 ports can be used for general I/O with selectable direction for each bit, or these lines can be used for specialized functions.

## 3.4 ADC

An 8bits SAR-ADC is integrated in the BK3231S. Total 8 channels can be selected used for ADC transfer. The ADC supports continue mode and single transfer mode, and the sample rate can be 1 KHz to 32KHz. In single transfer mode, it will generate interrupt every time after transform.

The ADC has four work modes they are sleep mode, single mode, and software mode and continue mode.

IDLE mode(mode==00): ADC is in idle state.

Single mode(mode==01): The ADC will enter idle mode when transfer is done and waiting MCU to read the result. You should write mode=1 again for another transfer.

Controlled by software (mode==10): In this mode, interrupt will be triggered after transfer and wait MCU to read. The interrupt will be cleared after MCU read, and then the transfer will start again.

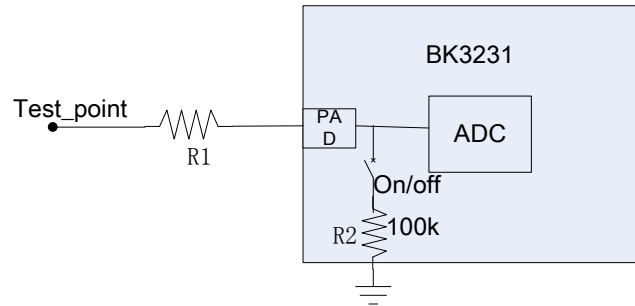
Continue mode(mode==11):The ADC will work at the sample rate set by register. The sample rate can be calculated by the next formula:

$$F_{\text{sample}} = \text{input ADC clock} / (2^{(\text{ADC\_CLK\_RATE}+2)} / 36(\text{or } 18))$$

The highest sample rate is 32k

The local interrupt flag of ADC need not be cleared by software; it will be set after transform and be cleared after the result has been read out. But the ADC INTstored ICU should be cleared after the ADC INT service finished.

The range of input voltage is from 0v to 1.5V. If the input voltage more than 1.5V, a resistor can be added to decrease the input voltage like the next diagram.



Note: There are eight GPIO can be ADC input. When used as this:

Voltage=data [9:0]/448; the saturate voltage is 1.5 volt.

### 3.5 UART

The UART interface has 128 bytes FIFO for both TX and RX. It will generate interrupt request when there is risk or event of FIFO underflow or overflow. For the RX, it will generate interrupt if found parity bit check error or stop bit check error.

When the UART RX line goes from idle state ('HIGH') to active state ('LOW') for a set UART clock cycle, it will generate wake up interrupt to activate MCU clock.

### 3.6 I2C-SMBus

The I2C I/O interface is a two-wire, bi-directional serial bus. The I2C is compliant with the System Management Bus Specification, version 1.1, and compatible with the I C serial bus. Reads and writes to the interface by the system controller are byte oriented with the I2C interface autonomously controlling the serial transfer of the data.

Data can be transferred at up to 1/10th of the system clock as a master or slave (this can be faster than allowed by the I2C specification, depending on the system clock used). A method of extending the clock-low duration is available to accommodate devices with different speed capabilities on the same bus.

The I2C interface may operate as a master and/or slave, and may function on a bus with multiple masters. The I2C provides control of SDA (serial data), SCL (serial clock) generation and synchronization, arbitration logic, and START/STOP control and generation.

It is assumed the reader is familiar with the I2C-Bus Specification -- Version 2.0 and system Management Bus Specification -- Version 1.1.

The bi-directional SCL (serial clock) and SDA (serial data) lines must be connected to a positive power supply voltage through a pull-up resistor or similar circuit. Every device connected to the bus must have an open-drain or open-collector output for both the SCL and SDA lines, so that both are pulled high (recessive state) when the bus is free.

### **3.7 SPI**

The Enhanced Serial Peripheral Interface (SPI) provides access to a flexible, full-duplex synchronous serial bus. SPI can operate as a master or slave device in both 3-wire or 4-wire modes, and supports multiple masters and slaves on a single SPI bus. The slave-select (NSS) signal can be configured as an input to select SPI in slave mode, or to disable Master Mode operation in a multi-master environment, avoiding contention on the SPI bus when more than one master attempts simultaneous data transfers. NSS can also be configured as a chip-select output in master mode, or disabled for 3-wire operation. Additional general purpose port I/O pins can be used to select multiple slaves.

There are four pins for SPI interface. The master-out, slave-in (MOSI) signal is an output from a master device and an input to slave devices. It is used to serially transfer data from the master to the slave. This signal is an output when SPI is operating as a master and an input when SPI is operating as a slave. Data is transferred most-significant bit first. When configured as a master, MOSI is driven by the MSB of the shift register in both 3- and 4-wire mode.

The master-in, slave-out (MISO) signal is an output from a slave device and an input to the master device. It is used to serially transfer data from the slave to the master. This signal is an input when SPI is operating as a master and an output when SPI is operating as a slave. Data is transferred most-significant bit first. The MISO pin is placed in a high-impedance state when the SPI module is disabled and when the SPI operates in 4-wire mode as a slave that is not selected. When acting as a slave in 3-wire mode, MISO is always driven by the MSB of the shift register.

In slave mode, the data on MOSI are sampled at the middle of period of every bit. In master mode, the data on MISO are sampled at the last clock period to acquire the maximal setup time.

## 3.8 PWM Timer

There are three timers, two of which is 16 bit and can be works as PWM waveform generator, while the other one is 20bit timer. The PWM waveform can be output to GPIO to drive external device such as LED.

## 3.9 Watch dog

The watch dog is used to reset the whole chip when the firmware runs out of order.

# 4 Electrical Specifications

## 4.1 General Specification

**Table 4 General Characteristics**

Name	Parameter (Condition)	Min	Typical	Max	Unit	Comment
<b>Operating Condition</b>						
VCC	Voltage	1.8	3.0	3.6	V	
TEMP	Temperature	-20	+27	+80	°C	
<b>Digital input Pin</b>						
VIH	High level	VCC-0.3		VCC+0.3	V	
VIL	Low level	VSS		VSS+0.3	V	
<b>Digital output Pin</b>						
VOH	High level (IOH=-0.25mA)	VCC- 0.3		VCC	V	
VOL	Low level(IOL=0.25mA)	VSS		VSS+0.3	V	

## 4.2 BLE mode

**Table 5 BLE mode RF Characteristics**

Name	Parameter (Condition)	Min	Typical	Max	Unit	Comment
<b>Normal condition</b>						
IVDD	Deep sleep		TBD		uA	
IVDD	Active RX		TBD		mA	
IVDD	Active TX @ 2 dBm output power		TBD		mA	
<b>Transmitter</b>						
PRF	Output power		4	5	dBm	
PBW	Modulation 20 dB bandwidth		1		MHz	
<b>Receiver</b>						
Max Input	1 E-3 BER	0			dBm	
RXSENS	1 E-3 BER sensitivity		-89		dBm	
IIP3	IIP3, Pin=-63 dBm; Punwant=-39 dBm; f0=2f1-f2, f2-f1=3 MHz or 4 MHz or 5 MHz		TBD		dBm	



C/ICO	Co-channel C/I			TBD	dB	
C/I1ST	ACS C/I 1MHz			TBD	dB	
C/I2ND	ACS C/I 2MHz			TBD	dB	
C/I3RD	ACS C/I 3MHz			TBD	dB	
C/I1STI	ACS C/I Image channel			TBD	dB	
C/I2NDI	ACS C/I 1 MHz adjacent to image channel			TBD	dB	

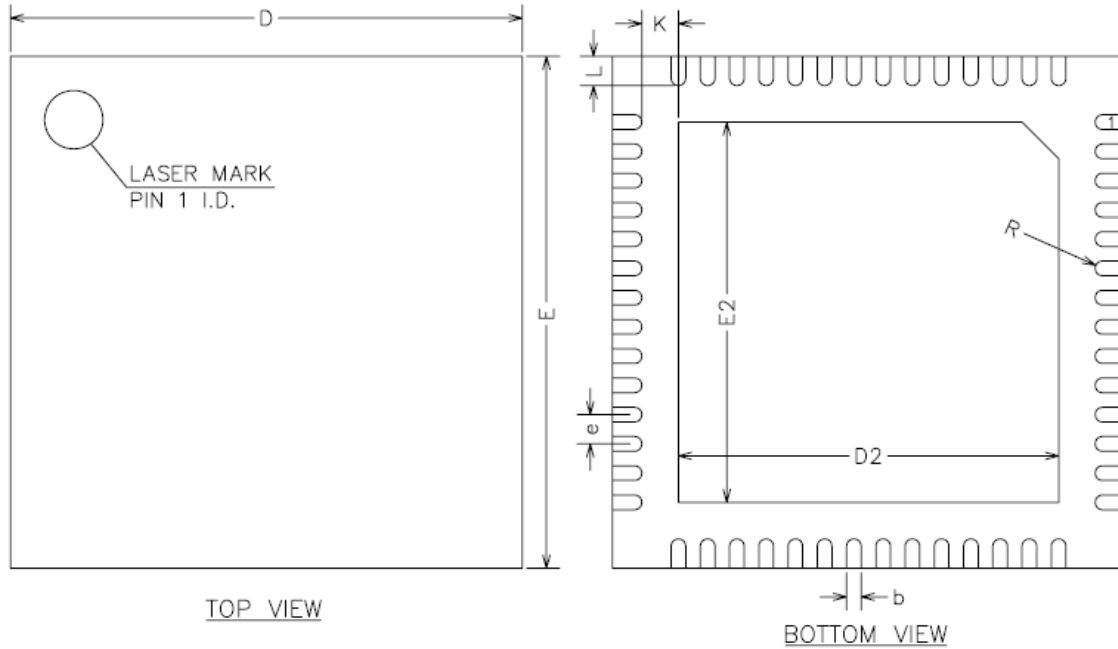
## 4.3 BR mode

Table 6 BR mode RF Characteristics

Name	Parameter (Condition)	Min	Typical	Max	Unit	Comment
<b>Normal condition</b>						
IVDD	Deep sleep		TBD		uA	
IVDD	Active RX		TBD		mA	
IVDD	Active TX @ 2 dBm output power		TBD		mA	
<b>Transmitter</b>						
PRF	Output power		2	5	dBm	
PBW	Modulation 20 dB bandwidth		1		MHz	
<b>Receiver</b>						
Max Input	1 E-3 BER	0			dBm	
RXSENS	1 E-3 BER sensitivity		-86		dBm	
IIP3	IIP3, Pin=-63 dBm; P <sub>unwant</sub> =-39 dBm; f <sub>0</sub> =2f <sub>1</sub> -f <sub>2</sub> , f <sub>2</sub> -f <sub>1</sub> =3 MHz or 4 MHz or 5 MHz		TBD		dBm	
C/ICO	Co-channel C/I			11	dB	
C/I1ST	ACS C/I 1MHz			0	dB	
C/I2ND	ACS C/I 2MHz			-30	dB	
C/I3RD	ACS C/I 3MHz			-40	dB	
C/I1STI	ACS C/I Image channel			-9	dB	
C/I2NDI	ACS C/I 1 MHz adjacent to image channel			-20	dB	

## 5 Package Information

### 5.1 QFN 7X7 56PIN:



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0	0.02	0.05
A3	0.20REF		
b	0.15	0.20	0.25
D	6.90	7.00	7.10
E	6.90	7.00	7.10
D2	5.05	5.20	5.35
E2	5.05	5.20	5.35
e	0.30	0.40	0.50
K	0.20	-	-
L	0.35	0.40	0.45
R	0.09	-	-



SIDE VIEW

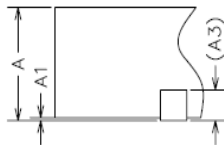
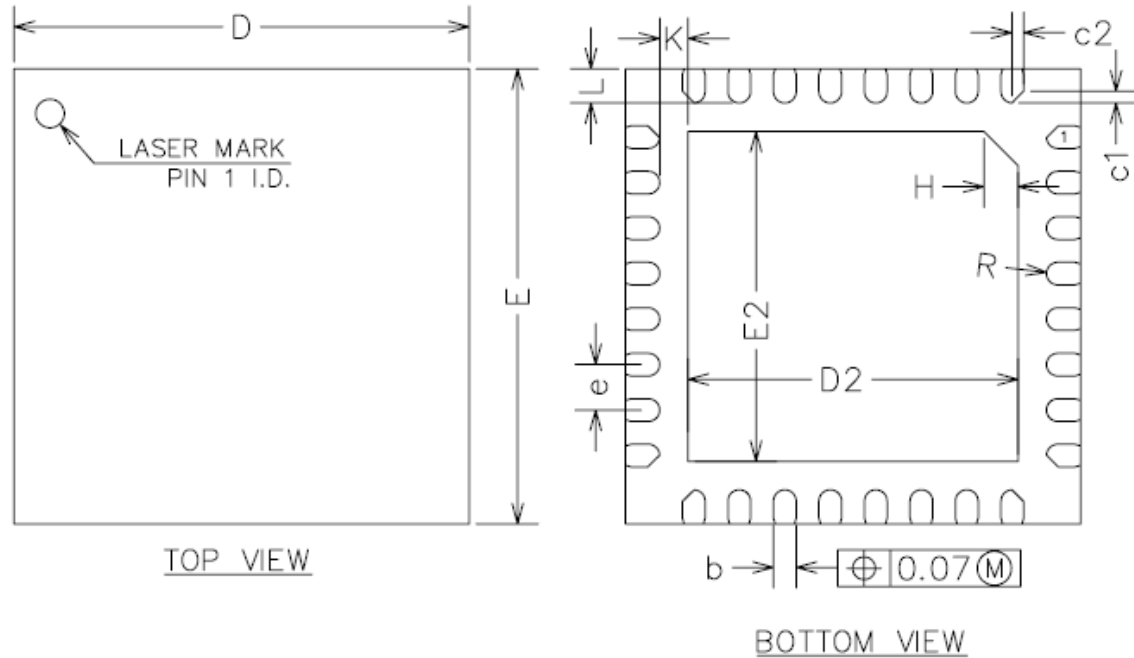


Figure 4 BK3231S QFN56Pin Package Information

## 5.2 QFN4X4 32PIN:



COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.80	0.85	0.90
A1	0	0.02	0.05
A2	0.60	0.65	0.70
A3	0.20REF		
b	0.15	0.20	0.25
D	3.90	4.00	4.10
E	3.90	4.00	4.10
D2	2.80	2.90	3.00
E2	2.80	2.90	3.00
e	0.30	0.40	0.50
H	0.30REF		
K	0.25REF		
L	0.25	0.30	0.35
R	0.09	-	-
c1	-	0.10	-
c2	-	0.10	-

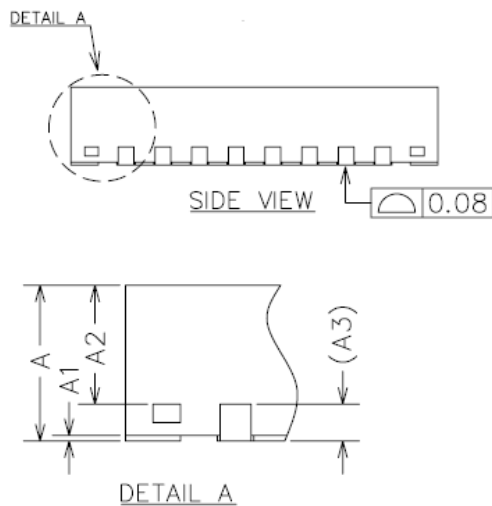


Figure 5 BK3231S QFN32Pin Package Information

## 6 Application Schematic

### 6.1 QFN7X7 56PIN:

TBD

### 6.2 QFN4X4 32PIN:

TBD

## 7 Order Information

Table 6 Order Information

Part number	Package	Packing	Minimum Order Quantity
BK3231SQB	QFN7x7-56Pin	Tape Reel	3000
BK3231SQ32	QFN 4mmx4mm 32-Pin	Tape Reel	10K

## 8 Contact Information

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